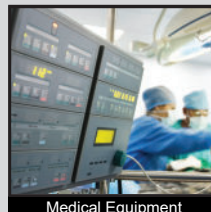
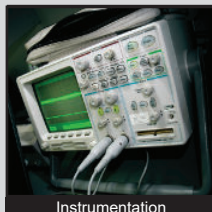
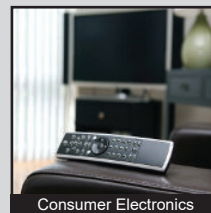
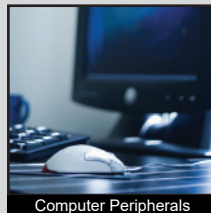
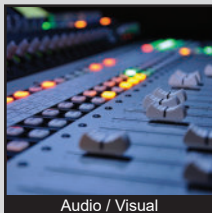


TL1017 SERIES TACT SWITCH

ANTI-VANDAL SWITCHES
DETECTOR SWITCHES
DIP SWITCHES
KEYLOCK SWITCHES
NAVIGATION SWITCHES
PUSHBUTTON SWITCHES
ROCKER SWITCHES
ROTARY SWITCHES
SLIDE SWITCHES
SNAP ACTION SWITCHES
TACTILE SWITCHES
TOGGLE SWITCHES
CAP OPTIONS



APPLICATIONS / MARKETS



RoHS

SPECIFICATIONS

Electrical Rating: 50mA, 12VDC
Contact Resistance: 100mΩ Max. (Initial)
Insulation Resistance: 100MΩ Min. at 500VDC
Dielectric Strength: 250VAC for 1 Minute
Life Cycles: 200,000 cycles for 160gf
 100,000 cycles for 260gf
Operating Temperature: -20°C to 70°C
Storage Temperature: -30°C to 80°C
Travel: 0.15mm ± 0.1mm
Operating Force: 160gf ± 50gf; 260gf ± 50gf
Function: SPST, Off-(On)
Packaging: Tape and Reel, 3,000 pcs/reel

FEATURES & BENEFITS

- Surface mount design
- Up to 200,000 cycle life expectancy
- Multiple actuation force options
- Mounting boss option
- Ground terminal option
- Tape and Reel packaging

PART NUMBER CONFIGURATOR

Series



TL1017

Actuator



A - 1.5mm

Bosses



A - Without Bosses
 B - With Bosses

Ground Terminal



A - Without Ground Terminal
 B - With Ground Terminal

Actuation Force



F160 - 160 gf - Black
 F260 - 260 gf - Red

Contact Plating



Q - Silver

Termination



G - Gull-wing

Specifications subject to change without notice 4.1.2023



E-SWITCH®

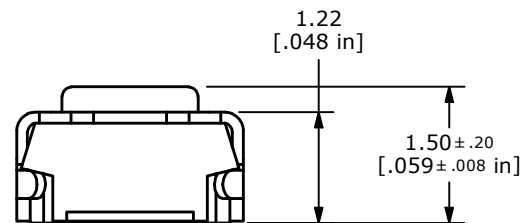
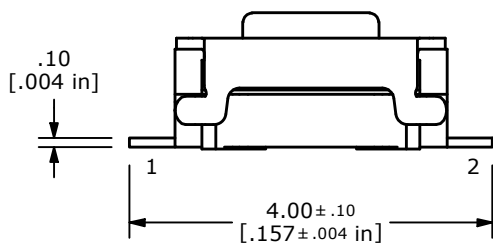
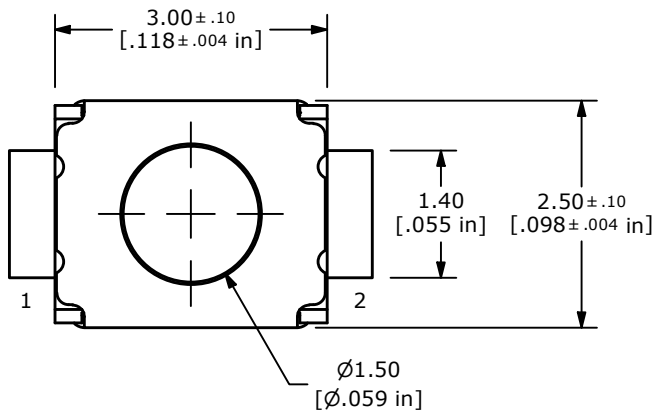
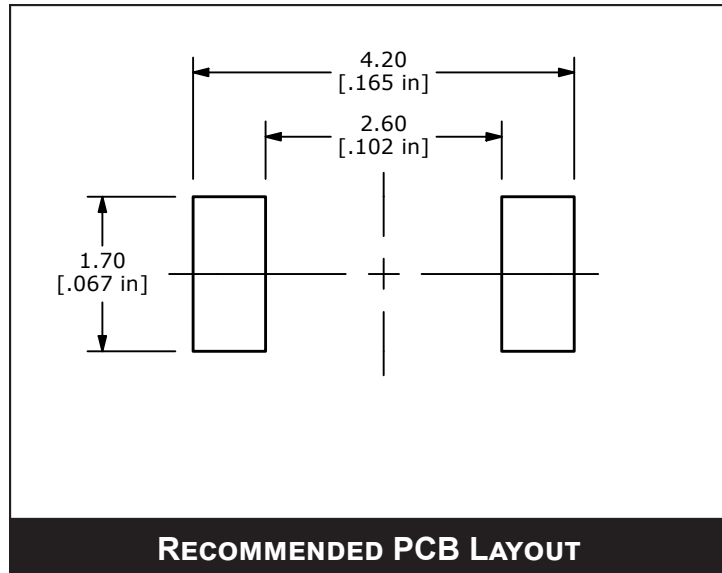
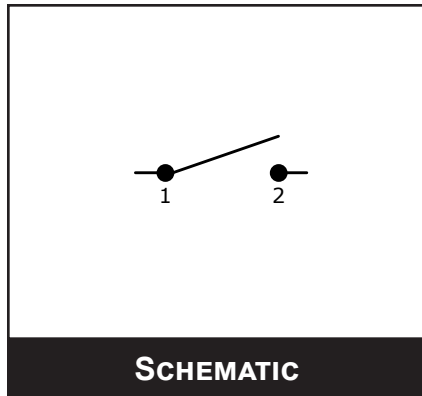
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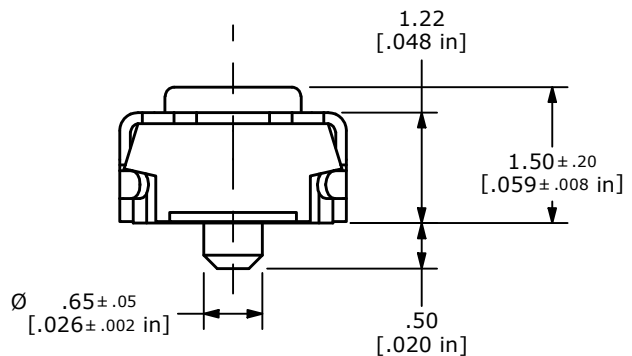
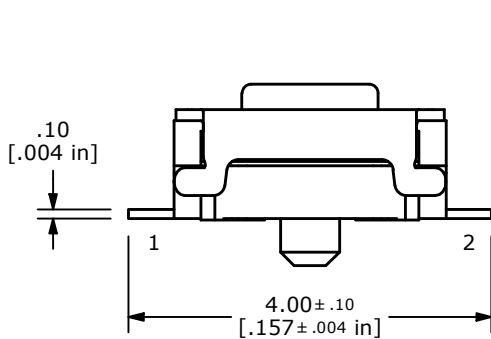
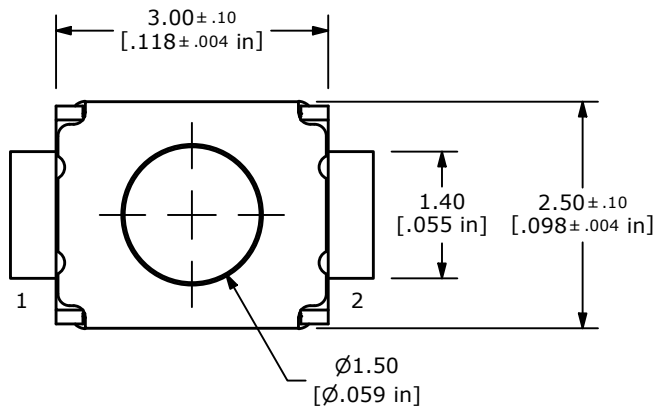
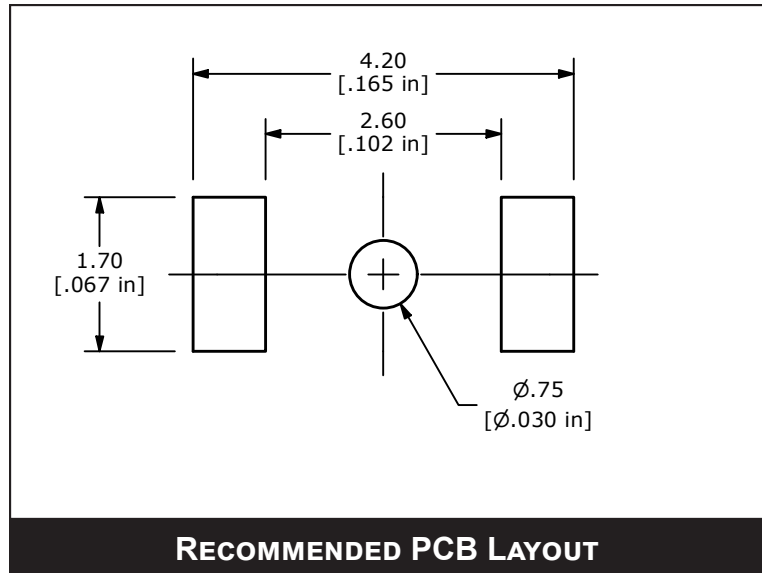
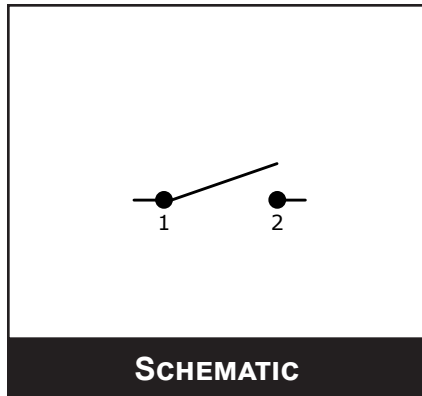
TL1017 SERIES TACT SWITCH

BODY DIMENSIONS WITHOUT BOSSES AND GROUND TERMINAL



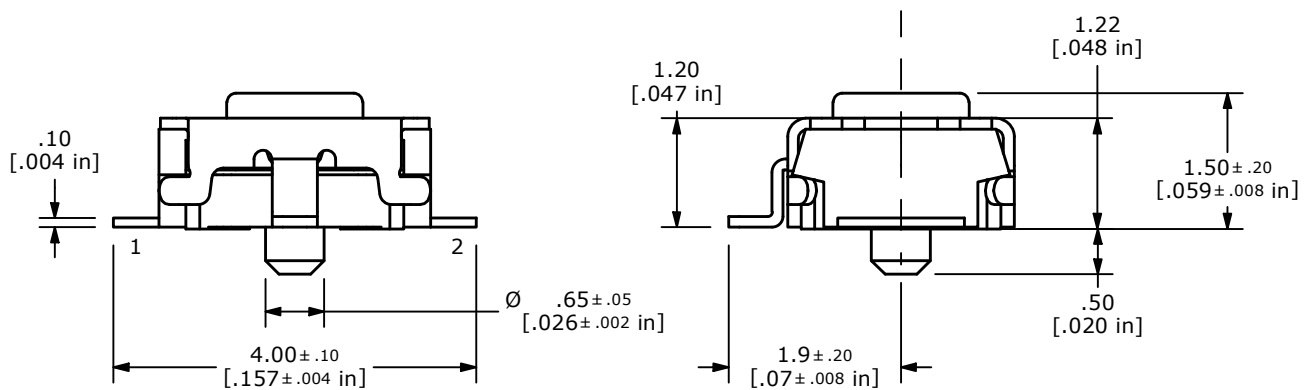
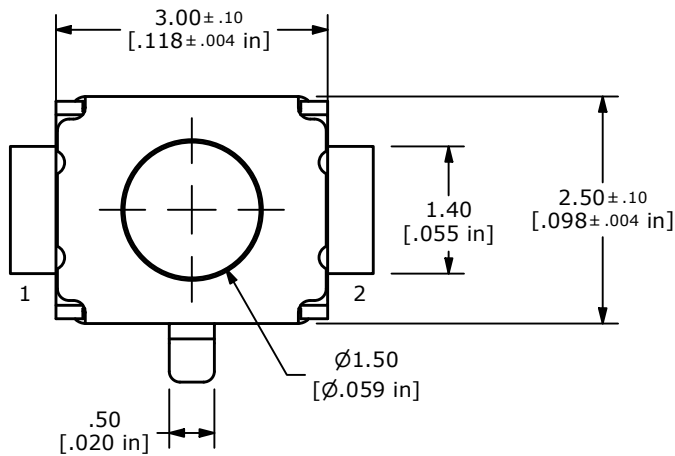
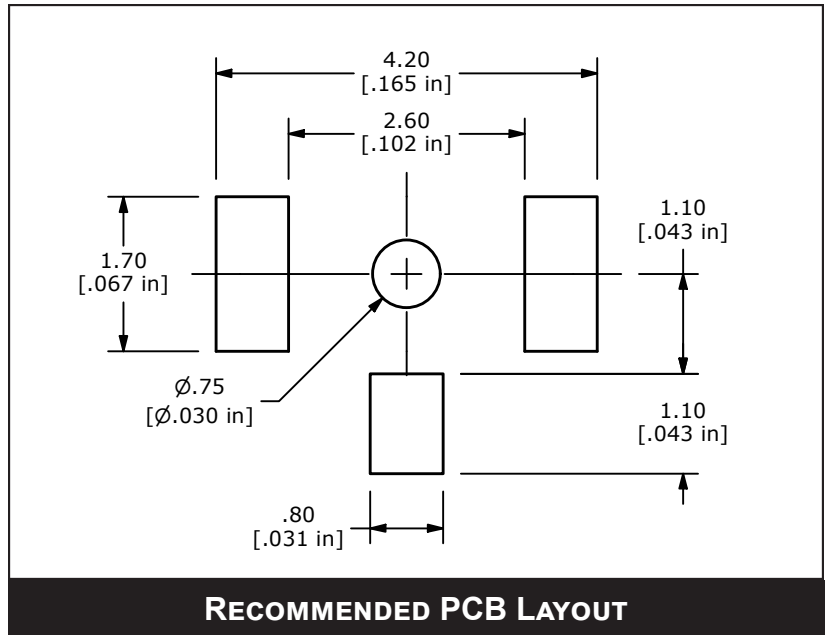
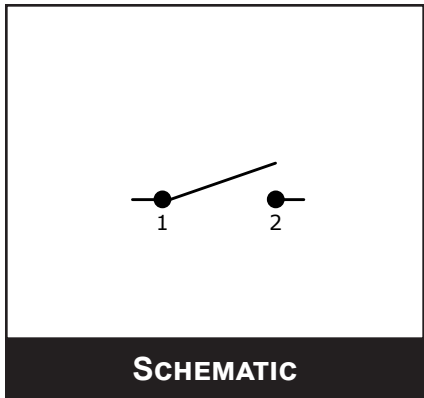
TL1017 SERIES TACT SWITCH

BODY DIMENSIONS WITH BOSSES AND WITHOUT GROUND TERMINAL



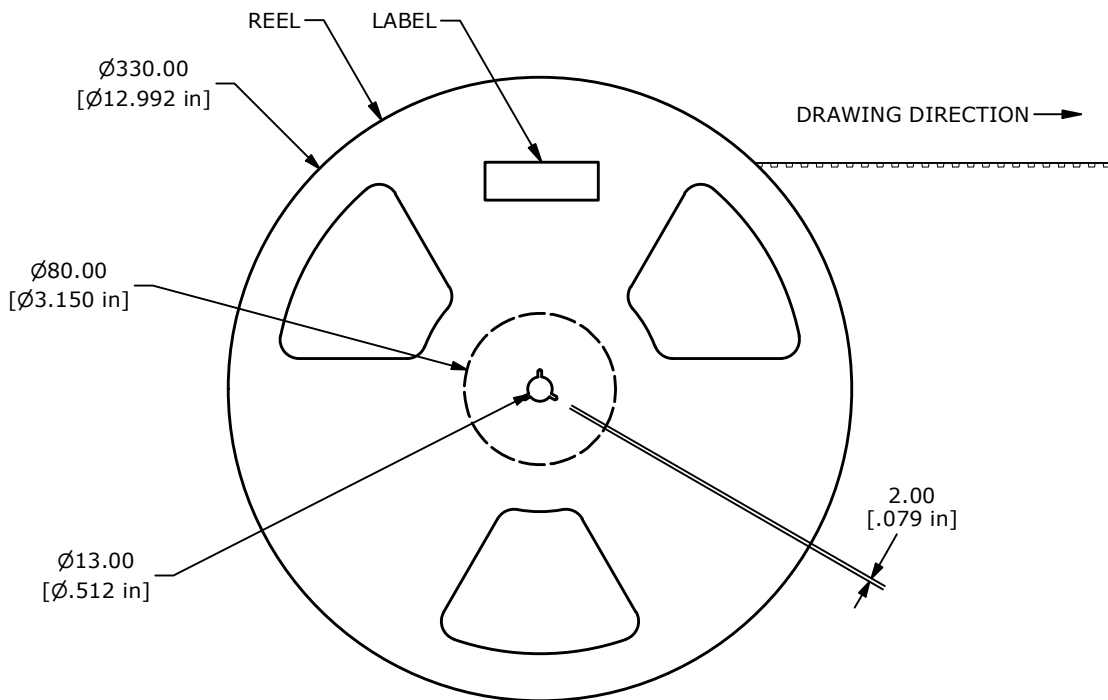
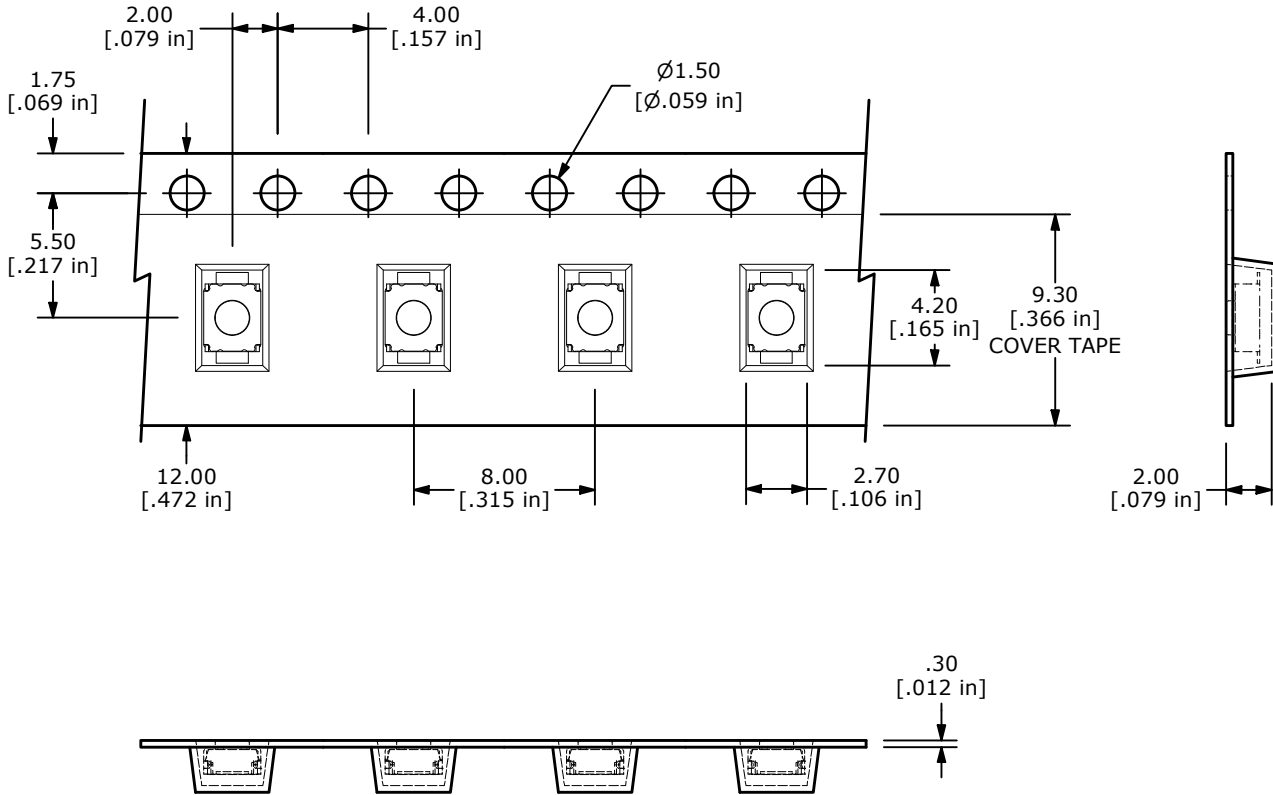
TL1017 SERIES TACT SWITCH

BODY DIMENSIONS WITH BOSSES AND GROUND TERMINAL



TL1017 SERIES TACT SWITCH

BODY DIMENSIONS TAPE AND REEL



TL1017 SERIES TACT SWITCH

RECOMMENDED SOLDER PROCESS

Most contamination problems can be prevented by exercising care during the cleaning and soldering process. Care should be taken not to immerse or spray unsealed switches during flux removal. Contact E-Switch for specific soldering recommendations and specifications not shown. Generalized soldering procedures are outlined below.

“TYPICAL” SMT REFLOW (Pb and Pb-Free)

Profile Feature	Sn-Pb Eutectic Assembly	Pb-Free Assembly
Average Ramp-Up Rate ($T_{s_{max}}$ to T_p)	3 °C/second max.	3 °C/second max.
Preheat		
-Temperature Min ($T_{s_{min}}$)	100 °C	150 °C
-Temperature Max ($T_{s_{max}}$)	150 °C	200 °C
-Time ($t_{s_{min}}$ to $t_{s_{max}}$)	60-120 seconds	60-180 seconds
Time Maintained above:		
-Temperature (T_L)	183 °C	217 °C
-Time (t_L)	60-150 seconds	60-150 seconds
Time within 5 °C of actual Peak Temperature (t_p)	10-30 seconds	20-40 seconds
Ramp-Down Rate	6 °C/second max.	6 °C/second max.
Time 25 °C to Peak Temperature	6 minutes max.	8 minutes max.

Note 1: All temperatures refer to topside of the package, measured on the package surface.

